

Bill of Materials

64 Button Mutual Capacitance Touch Panel with CapTivate Technology

TIDM-CAPTIVATE-64-BUTTON

Item	Qty	Reference	Part Description	Manufacturer	Manufacturer Part Number	Note
PCB	1		Printed Circuit Board	Any	TIDM-CAPTIVATE-64-BUTTON	
			Connector, 3x16, 100			
1	1	CapTIvate Panel-Side Connector	mil, TH, RA, M	Harting	9231486921	
FID1, FID2, FID3, FID4	4	N/A	Fiducial mark	N/A	N/A	There is nothing to buy or mount
			Bumpon, Cylindrical,			
H1, H2	2	Black Bumpon	0.312 x 0.200	3M	SJ61A1	

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